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Number 1

- 2 Access this journal online
- 3 Note from the publisher
- 4 A sequential triggering technique in cascaded current source for low power 12-b D/A converter
Zhi-Yuan Cui, Ho-Yong Choi, Tae-Won Cho and Nam-Soo Kim
- 8 Study of electrical characteristics of ZnO Schottky photodiode on Si substrate
L.S. Chuah, Z. Hassan, S.S. Tneh and S.G. Teo
- 12 Evaluation of the electrical properties under extreme stress in photovoltaic solar modules
J. Sidawi, N. Abboud, G. Jelian, R. Habchi and C. Salame
- 17 Temperature cycling analysis for ball grid array package using finite element analysis
Muhammad Nubli Zulkifli, Zul Azhar Zahid Jamal and Ghulam Abdul Quadir
- 29 Design-for-reliability implementation in microelectronics packaging development
Liyu Yang, Rui Niu, Jinsong Xie, Bin Qian, Baishi Song, Qingan Rong and Joseph Bernstein
- 41 A novel application of planar-type meander sensors
Snezana M. Djuric, Laszlo F. Nagy, Mirjana S. Damjanovic, Nikola M. Djuric and Ljiljana D. Zivanov
- 50 Functional room temperature metal (Al or Pd)-ZrO₂ (smooth or porous surface)-Si MOS capacitor O₂ sensor
Mun Teng Soo, Kuan Yew Cheon and Ahmad Fauzi Mohd Noor
- 58 Influence of Mg²⁺ substitution on the magnetic and electrical properties of Li-Zn ferrite thick films synthesized with PVA matrix
M.K. Rendale, S.D. Kulkarni, D.C. Kulkarni and Vijaya Puri
- 66 The effect of low temperature thermal annealing on the properties of organic light-emitting device
Chun-lin Zhang, Yong Zhang, Fang-cong Wang, Ying Wei, Xiao-yun Jia and Su Liu
- 71 Industry news
- 76 New products
- 79 Conferences and exhibitions
- 83 Appointments
- 85 Forthcoming events

